an inner wall within the perimeter of the end surface and including an outer surface spaced from and opposing the inner peripheral surface of the peripheral side wall, and an inner surface facing the center of the housing; and

a plurality of conductive leads inserted through the peripheral side wall and the inner wall.

48. The semiconductor die carrier according to claim 47, further comprising a cavity extending between the inner peripheral surface of the peripheral side wall and the outer surface of the inner wall.

49. The semiconductor die carrier according to claim 48, further comprising a filler in the cavity to seal an interior of said housing.

50. (Amended) A semiconductor die carrier comprising:

a housing for holding at least one semiconductor die and including:

an end surface having a perimeter;

a peripheral side wall connected to the end surface, extending about the perimeter of the end surface and including an outer peripheral surface and an inner peripheral surface; and

an inner wall within the perimeter of the end surface and including an outer surface spaced from and opposing the inner peripheral surface of the peripheral side wall, and an inner surface facing the center of the housing;

a plurality of conductive leads inserted through the peripheral side wall and the inner wall;

a cavity extending between the inner peripheral surface of the peripheral side wall and the outer surface of the inner wall; and

a filler in the cavity to seal an interior of said housing, wherein the filler comprises an adhesive.

51. The semiconductor die carrier according to claim 49, further comprising a semiconductor die received on the end surface; and

the inner wall encircles the semiconductor die.

52. (Amended) A semiconductor die carrier comprising:

a housing for holding at least one semiconductor die and including:

an end surface having a perimeter;

a peripheral side wall connected to the end surface, extending about the perimeter of the end surface and including an outer peripheral surface and an inner peripheral surface;

an inner wall within the perimeter of the end surface and including an outer surface spaced from and opposing the inner peripheral surface of the peripheral side wall, and an inner surface facing the center of the housing; and

a plurality of spaced-apart ledges extending from the inner surface of the inner wall;

a plurality of conductive leads inserted through the peripheral side wall and the inner wall;

a cavity extending between the inner peripheral surface of the peripheral side wall and the outer surface of the inner wall;

a filler in the cavity to seal an interior of said housing; and

a semiconductor die received on the end surface and encircled by the inner wall.

53. The semiconductor die carrier according to claim 47, wherein the leads are arranged in multiple spaced apart rows.

54. The semiconductor die carrier according to claim 47, wherein the plurality of leads each comprise a substantially L-shape.

55. The semiconductor die carrier according to claim 47, wherein the peripheral side wall comprises a first material and the end surface comprises a second material different from the first material.